

AMENDMENTS TO THE CLAIMS

The following listing of claims replaces all prior versions of claims in the application.

1. (Currently Amended): A mounting apparatus, comprising:

a table, on which a ring shaped first adherend and a plate shaped second adherend are disposed, the second adherend being disposed inside of the first adherend;

a supporting device capable of supporting a strip material including a film stuck on a surface of a base sheet;

a pre-cutting device having a first member located on a film side of the strip material and a second member located on a base sheet side of the strip material, the first member having a blade which forms a closed loop cut on the film, said closed loop having a width less than a width of said film, [[,]] thereby forming a pre-cut portion of said film;

a peeling device for peeling the pre-cut portion from said base sheet, said peeling device being located downstream of said pre-cutting device in the sheet feeding direction of the strip material; and

a press roller positioned at a downstream end of said peeling device, in the sheet feeding direction, for pressing the pre-cut portion so as to stick said pre-cut portion to the first and second adherends; [[,]]

wherein said pre-cutting device is configured such that the cut is made from a face of said film opposite the face of said film which is to be peeled from the base sheet by said peeling device, and

wherein said press roller is configured to press the pre-cut portion on the face of said film opposite the face of said film peeled from the base sheet by said peeling device.

2. (Cancelled)

3. (Withdrawn): A mounting method in which a ring frame is disposed on a table, a semiconductor wafer is disposed in an inside area of the ring frame, and a dicing tape is stuck onto said ring frame to fix the semiconductor wafer to the ring frame, comprising the steps of:

forming a cut in said film in accordance with the size of said ring frame in a process of feeding out a strip material attaching a film for forming dicing tapes stuck on one surface of a base sheet;

peeling off the dicing tape formed inside said cut from the base sheet; and

moving the dicing tape and said table relative to each other to stick said dicing tape onto the semiconductor wafer and the ring frame, thereby fixing the semiconductor wafer to the ring frame.

4. (Withdrawn): The mounting method according to claim 3, wherein a tension control means is disposed between said supporting means and a pre-cut means, wherein,

the tension control means comprises a dancer roller, which is movable vertically so as to allow said strip material to be fed out toward said sticking means while giving tension due to its

own weight to said strip material, and first and second sensors for detecting a raised position and a lowered position of the dancer roller respectively, and wherein,

the following operations are repeated; i.e., when the first sensor detects said dancer roller at the raised position, said supporting means feeds out the strip material of a predetermined amount to lower the dancer roller, and when the second sensor detects the dancer roller at the lowered position, said supporting means stops feeding out the strip material therefrom.

5-7. (Cancelled)

8. (Previously Presented) The mounting apparatus according to claim 1, further comprising a winding device for continuously winding the strip material after peeling the pre-cut portions from the base sheet.

9. (Previously Presented) The mounting apparatus according to claim 1, wherein the first member is formed by a die roller having said blade which forms said closed loop, and the second member is a die receiving plate.

10. (Previously Presented) The mounting apparatus according to claim 8, wherein the first member is formed by a die roller having said blade which forms said closed loop, and the second member is a die receiving plate.

11. (Previously Presented) The mounting apparatus according to claim 1, wherein the first member is a die plate having said blade which forms said closed loop thereon and the second member is a movable roller.

12. (Previously Presented) The mounting apparatus according to claim 8, wherein the first member is a die plate having said blade which forms said closed loop thereon and the second member is a movable roller.

13. ~~14.~~ (Previously Presented) The mounting apparatus according to claim 1,
wherein the first member includes a rotation member capable of rotating about an axis parallel to the surface of the film and the second member is a receiving plate, and
wherein said blade which forms said closed loop is held by the free end side of the rotation member.

14. ~~15.~~ (Previously Presented) The mounting apparatus according to claim 8,
wherein the first member includes a rotation member capable of rotating about an axis parallel to the surface of the film and the second member is a receiving plate, and
wherein said blade which forms said closed loop is held by the free end side of the rotation member.